


APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

Title of Invention	METHOD AND DEVICE FOR CUTTING WIRE FORMED ON SEMICONDUCTOR SUBSTRATE		
Application Type : regular, utility Attorney Docket Number : 040103			
Correspondence address: Customer Number: 23850 			
Priority Data: Doc.No: 2003-361072; Country -JP ; Date: 2003-10-21 us-priority-claimed			
Inventors Information: <u>Inventor 1:</u> Applicant Authority Type: Inventor Citizenship: JP Given Name: Yukio Family Name: MARUTA Residence: City of Residence: Kasugai Country of Residence: JP Address-1 of Mailing Address: c/o FUJITSU VLSI LIMITED Address-2 of Mailing Address: 1844-2, Kozoji-cho 2-chome City of Mailing Address: Kasugai-shi, Aichi State of Mailing Address: Postal Code of Mailing Address: 487-0013 Country of Mailing Address: JP Phone: Fax: E-mail: <u>Inventor 2:</u> Applicant Authority Type: Inventor Citizenship: JP			

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Assignee 1:

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